Chip-to-Wafer direct-metallic-bonding technology developed at Leti used in customized 300mm device bonder

I-Micronews

CEA-Leti today announced a multi-partner project to demonstrate high-alignment-accuracy (<1µm) chip-to-wafer structures made by direct metallic bonding. Such structures are required for high-performance 3D integrated circuits and could enable a wide range of applications in microelectronics as well as in optoelectronics or MEMS.
SOURCE [1]

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http://www.mdtmag.com/news/2011/02/chip-wafer-direct-metallic-bonding-technology-developed-leti-used-customized-300mm-device-bonder

Links:
[1] http://www.i-micronews.com/lectureArticle.asp?id=6485